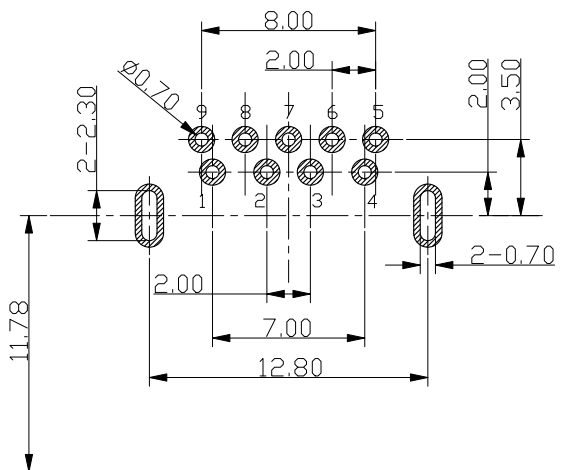
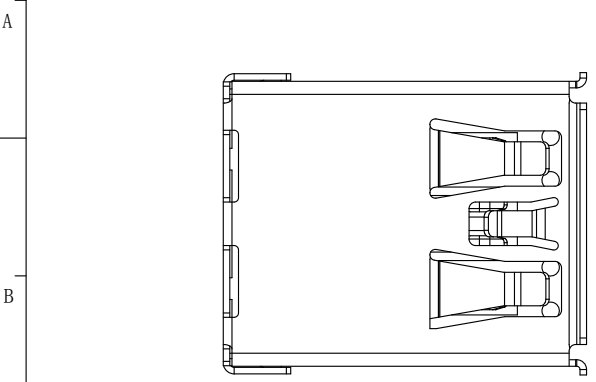


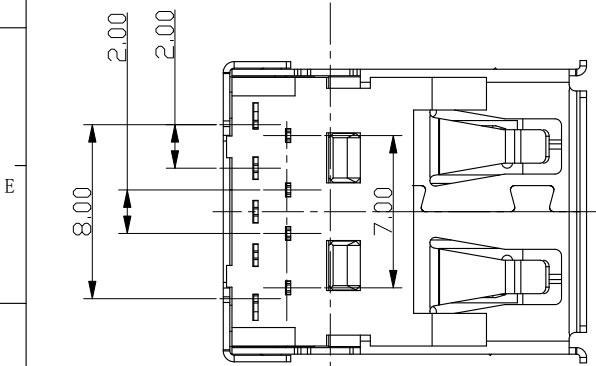
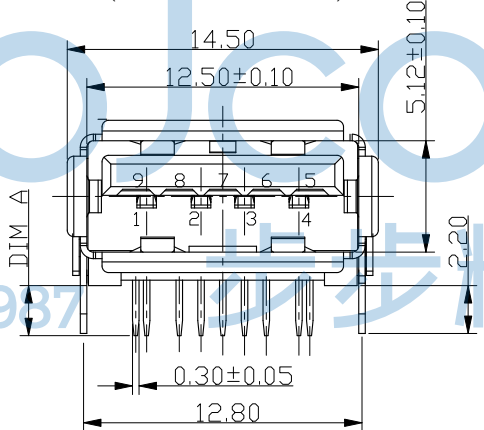
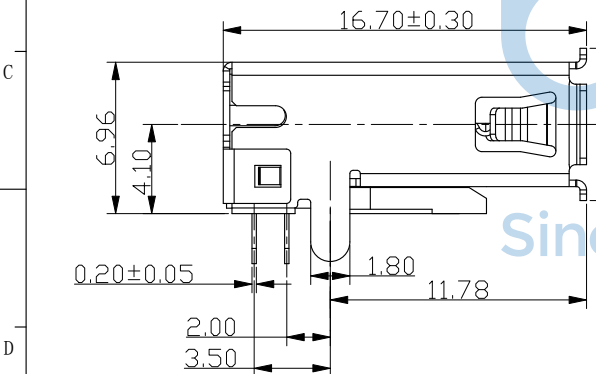
REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:

- MATERIAL:
 - INSULATOR:HIGH TEMPERATURE PLASTIC
 - CONTACT:BRONZE
 - SHELL:BRASS
- ELECTRICAL CHARACTERISTICS;
 - CONTACT RESISTANCE:30mΩ MAX
 - CONTACT CURRENT RATING:1.5A
 - DIELECTRIC WITHSTANDING VOLTAGE:100 V R. M. S.
 - INSULATION RESISTANCE 100 MΩ MIN
 - OPERATING TEMPERATURE:-20° C ~ 60° C
- MECHANICAL CHARACTERISTICS:
 - MATING FORCE:3.57kgf MAX
 - UNMATING FORCE:1.02kgf MIN
 - DURABILITY:MANDATORY:1,500 CYCLES
- PLATING
 - TERMINAL:
 - 50u" MIN NICKEL ALL OVER
 - 80u"MIN Tin ON SOLDER AREA
 - (1~30)u"Au ON CONTACT AREA
 - SHELL:80u"MIN. NICEL ALL OVER



RECOMMENDED PCBA LAYOUT
(TOLERANCE+±0.05)



DIMA
2.10
2.30



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

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PDWG.NO: 0471-1

APPD. JM_Zheng

CHKD. LYX

DR. TSP

深圳市步步精科技有限公司

NAME: USB 3.0 AF 90度 L=16.70 H=6.96 后两脚插 直脚 端子DIP 端子脚长2.3 镀金15U 卷边 LCP蓝胶 不锈钢外壳

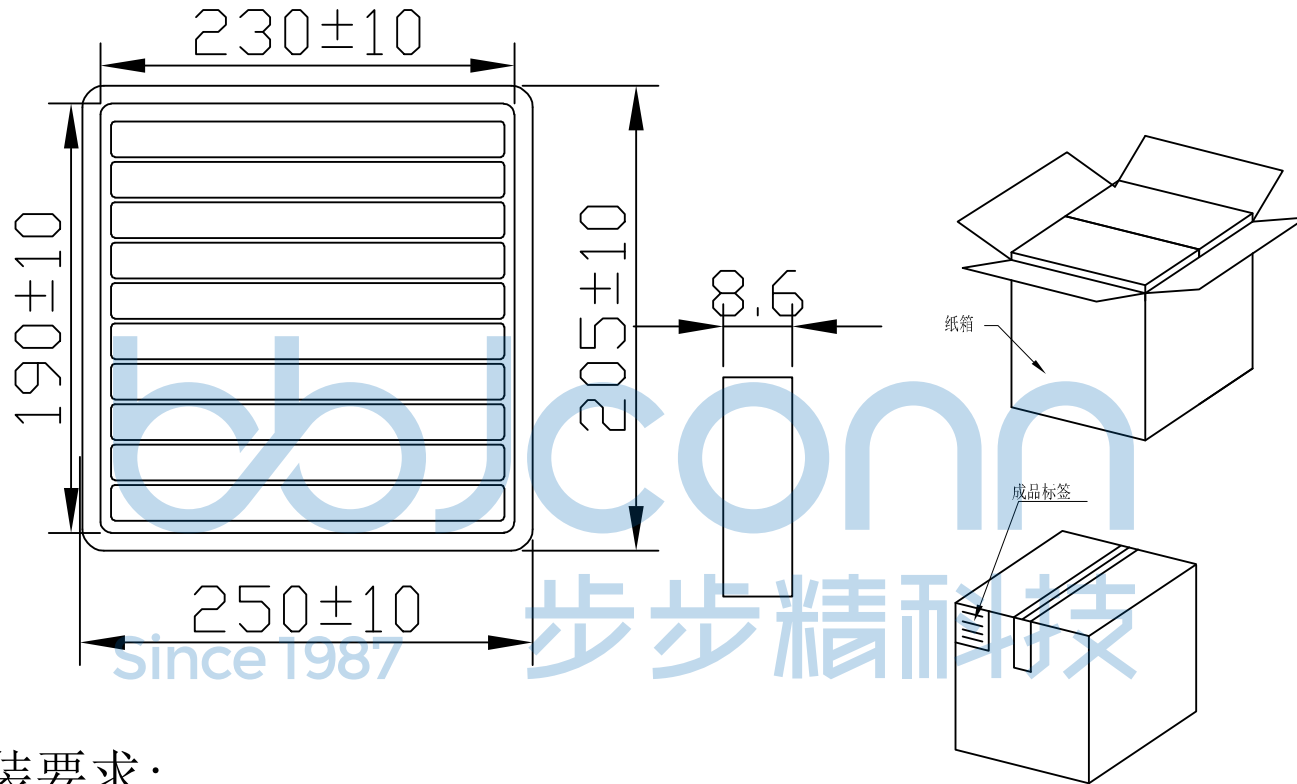
PJ. NO.: 127-272-090022-Y4G

SIZE: A4 DRW NO.:

FINISH: SEE NOTES MAT' L.: SEE NOTES

SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



纸箱规格: 350*210*290

1. 包装要求:
- 1.1 每盒吸塑盒包装100pcs;
 - 1.2 每20盘放一箱, 共计2000PCS;
 - 1.3 纸箱外贴上标签。

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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13 X°: ±3° .X°: ±2° .XX°: ±1°		NAME: USB 3.0 AF 90度 L=16.70 H=6.96 后两脚插 直脚 端子DIP 端子脚长2.3 镀金15U 卷边 LCP蓝胶 不锈钢外壳	
APPD.	JM_Zheng	P.J. NO.: 127-272-090022-Y4G SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES MAT' L.: SEE NOTES	
PDWG.NO:	0471-1	DR.	TSP
		SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/2